

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ru-Gun Liu</td> <td>05/22/2007</td> </tr> <tr> <td>Chih-Ming Lai</td> <td>05/22/2007</td> </tr> <tr> <td>Wen-Chun Huang</td> <td>05/24/2007</td> </tr> <tr> <td>Boren Luo</td> <td>05/28/2007</td> </tr> <tr> <td>I-Chang Shin</td> <td>05/24/2007</td> </tr> <tr> <td>Yao-Ching Ku</td> <td>05/18/2007</td> </tr> <tr> <td>Cliff Hou</td> <td>05/25/2007</td> </tr> </tbody> </table>		Name	Execution Date	Ru-Gun Liu	05/22/2007	Chih-Ming Lai	05/22/2007	Wen-Chun Huang	05/24/2007	Boren Luo	05/28/2007	I-Chang Shin	05/24/2007	Yao-Ching Ku	05/18/2007	Cliff Hou	05/25/2007
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RECEIVING PARTY DATA																	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.																
Street Address:	No. 8, Li-Hsin Rd. 6																
Internal Address:	Science-Based Industrial Park																
City:	Hsin-Chu																
State/Country:	TAIWAN																
Postal Code:	300-77																
PROPERTY NUMBERS Total: 1																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11748604</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11748604												
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CORRESPONDENCE DATA																	
Fax Number:	(214)200-0853																
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ATTORNEY DOCKET NUMBER:	24061.802																

CH \$40.00 11748604

PATENT

500323214

REEL: 019616 FRAME: 0649

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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ASSIGNMENT

WHEREAS, We,

- (1) **Ru-Gun Liu**, of Hsinchu City, Taiwan, R.O.C.;
- (2) **Chih-Ming Lai**, of Hsinchu City, Taiwan, R.O.C.;
- (3) **Wen-Chun Huang**, of Xi-Gang Xiang, Tainan County, Taiwan, R.O.C.;
- (4) **Boren Luo**, of Hsinchu City, Taiwan, R.O.C.;
- (5) **I-Chang Shin**, of Hsinchu City, Taiwan, R.O.C.;
- (6) **Yao-Ching Ku**, Hsinchu City, Taiwan, R.O.C.; and
- (7) **Cliff Hou**, Taipei, Taiwan, R.O.C.

have invented certain improvements in

MODEL IMPORT FOR ELECTRONIC DESIGN AUTOMATION

for which we have executed and filed an application for Letters Patent of the United States of America, on May 15, 2007, and which was assigned application serial number 11/748,604; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2006-0392 / 24061.802

Customer No.: 000042717

Inventor Name: I-Chang Shin

Residence Address: No. 8, Li-Hsin Rd. 6, Hsinchu Science Park
Hsinchu, Taiwan 300-77, R.O.C.

Dated: 5/24 2007

I-chang Shin
I-Chang Shin (Inventor Signature)

Inventor Name: Yao-Ching Ku

Residence Address: No. 8, Li-Hsin Rd. 6, Science Based Industrial Park
Hsinchu, Taiwan 300-77, R.O.C.

Dated: 5/18/2007

Yao-Ching Ku
Yao-Ching Ku (Inventor Signature)

Inventor Name: Cliff Hou

Residence Address: 4F #11, Lane 33, Section 1, Chien-Kwo North Road
Taipei, Taiwan, R.O.C.

Dated: 5/25/2007

Cliff Hou
Cliff Hou (Inventor Signature)